

AB357NT Photocoupler

FEATURES

- Opaque type, mini-flat package
- Subminiature type (The volume is smaller than that of our conventional DIP type by as far as 30%)
- Isolation voltage between input and output Viso: 3750Vrms
- Employs double transfer mold technology
- Package: 1000 pcs / reel
- Moisture sensitivity level: 4
- RoHS compliant

APPLICATIONS

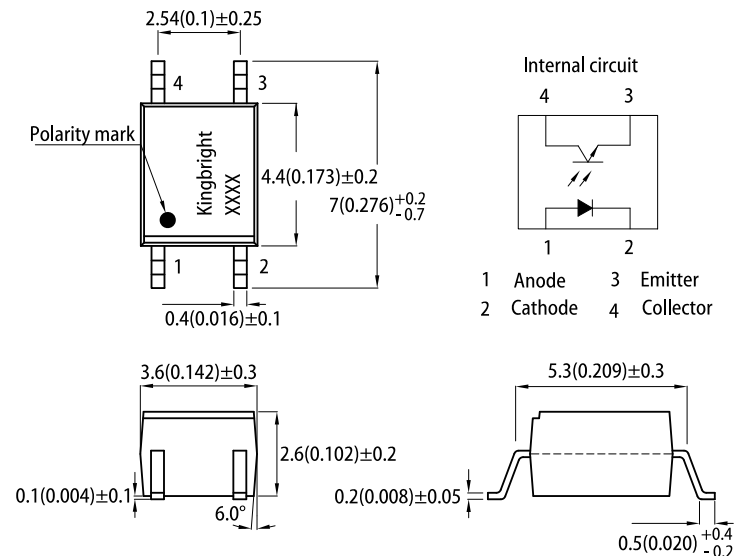
- Hybrid substrates that require high density mounting
- Programmable controllers

NOTES ON HANDLING

Cautions regarding electrical noise

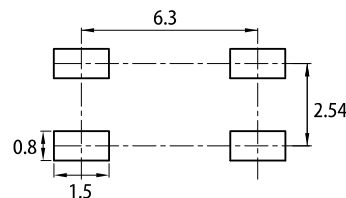
Please ensure the power supply is stable at all times. Even if the designed operating voltage is within specification limits, sudden voltage spikes at startup may damage the component.

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.15)



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.5(0.02") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Value			Unit	Test Conditions		
		Min.	Typ.	Max.				
Input	Forward Voltage	V _F	-	1.2	1.4	V	I _F =20mA	
	Peak Forward Voltage	V _{FM}	-	-	3.0	V	I _{FM} =0.5A	
	Reverse Current	I _R	-	-	10	μA	V _R =4V	
Output	Collector Dark Current	I _{CEO}	-	-	10 ⁻⁷	A	I _F =0mA, V _{CE} =20V	
Transfer Characteristics	Current Transfer Ratio	CTR	50	-	600	%	I _F =5mA, V _{CE} =5V	
	Collector-Emitter Saturation Voltage	V _{CE(sat)}	-	-	0.2	V	I _F =20mA, I _C =1mA	
	Response Time	Rise Time	t _r	-	4	18	μs	V _{CE} =2V, I _C =2mA R _L =100 Ω
		Fall Time	t _f	-	3	18	μs	

Note:

1. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at $T_A=25^{\circ}\text{C}$

Parameter		Symbol	Rating	Unit
Input	Forward Current	I_F	50	mA
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	70	mW
Output	Collector-Emitter Voltage	V_{CEO}	35	V
	Emitter-Collector Voltage	V_{ECO}	6	V
	Collector Current	I_C	50	mA
	Collector Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	170	mW
Isolation Voltage ^[1]		V_{iso}	3750	Vrms
Operating Temperature		T_{opr}	-30~+100	$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-40~+125	$^{\circ}\text{C}$

Notes:
 1. 40 to 60% RH, AC for 1 minute.
 2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

Rank Mark	CTR(%)
L	50 ~ 100
A	80 ~ 160
B	130 ~ 260
C	200 ~ 400
D	300 ~ 600
A or B	80 ~ 260
B or C	130 ~ 400
C or D	200 ~ 600
A,B or C	80 ~ 400
B,C or D	130 ~ 600
A,B,C or D	80 ~ 600
L,A,B,C,D or No mark	50 ~ 600

TECHNICAL DATA

Fig. 1 Current Transfer Ratio vs. Forward Current

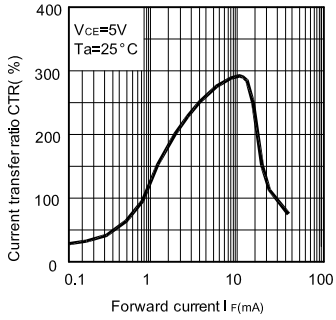


Fig. 2 Forward Current vs. Forward Voltage

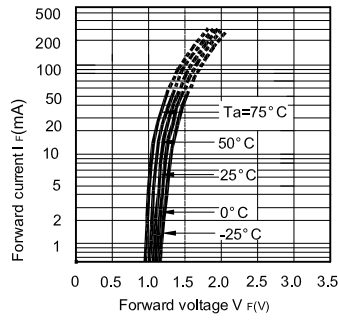


Fig. 3 Collector Current vs. Collector-Emitter Voltage

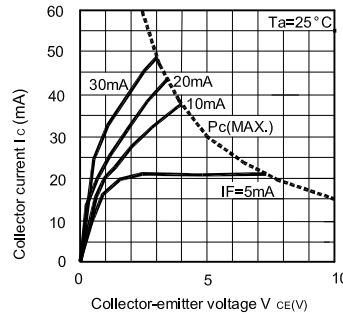


Fig. 4 Relative Current Transfer Ratio vs. Ambient Temperature

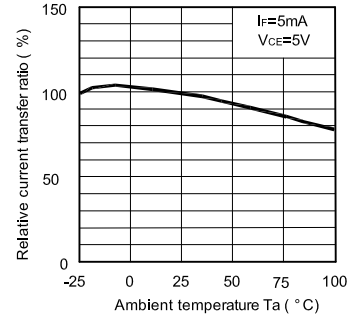


Fig. 5 Collector-Emitter Saturation Voltage vs. Ambient Temperature

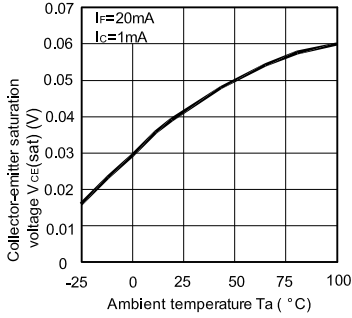


Fig. 6 Response Time vs. Load Resistance

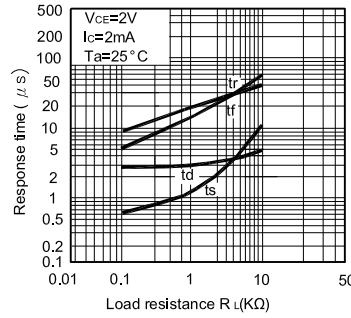


Fig. 7 Collector-Emitter Saturation Voltage vs. Forward Current

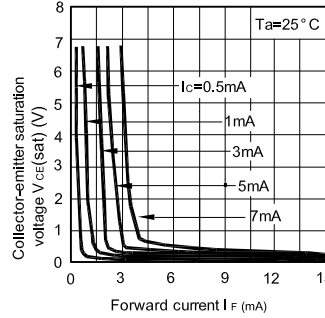
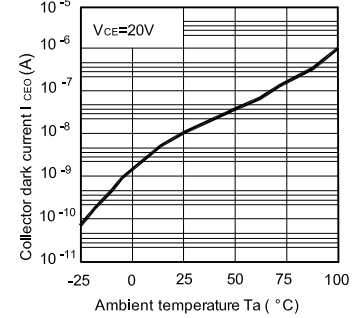
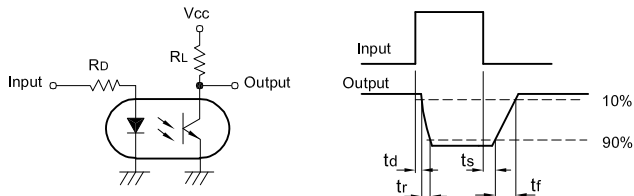


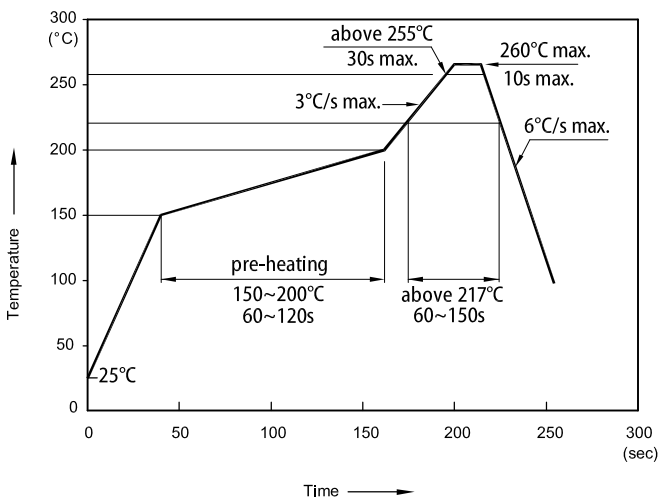
Fig. 8 Collector Dark Current vs. Ambient Temperature



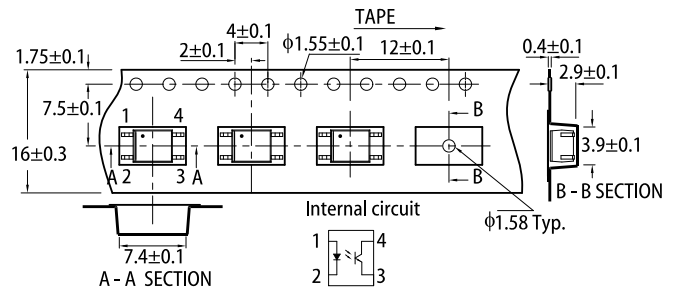
Test Circuit for Response Time



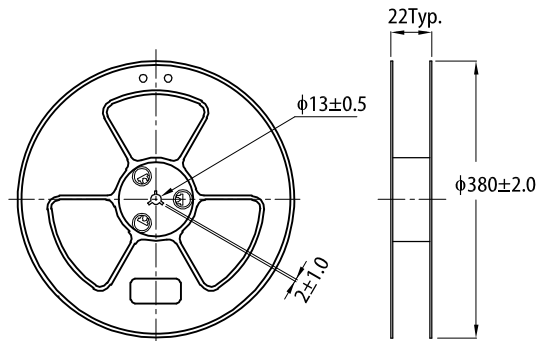
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



TAPE SPECIFICATIONS (units : mm)

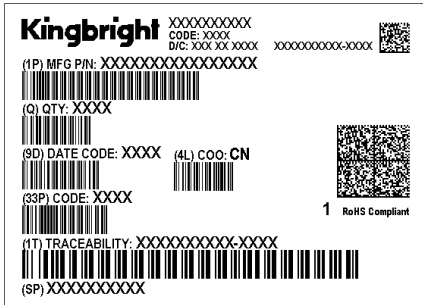
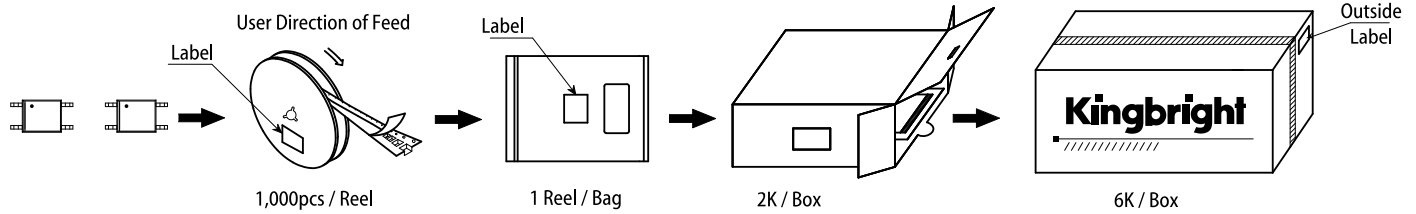


REEL DIMENSION (units : mm)



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



RESTRICTIONS ON PRODUCT USE

1. The information in this document represents typical usage and is provided for technical reference.
2. The information in this document is subject to change without notice. Please refer to the latest version of this document for the most updated information.
3. Please ensure this product is used in accordance with the electrical and environmental specifications and tolerances listed in this document. If the usage exceeds the specification range, Kingbright will not be responsible for any subsequent issues.
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